

3D Structuration of LTCC / Thick-Film Sensors and Fluidic Devices

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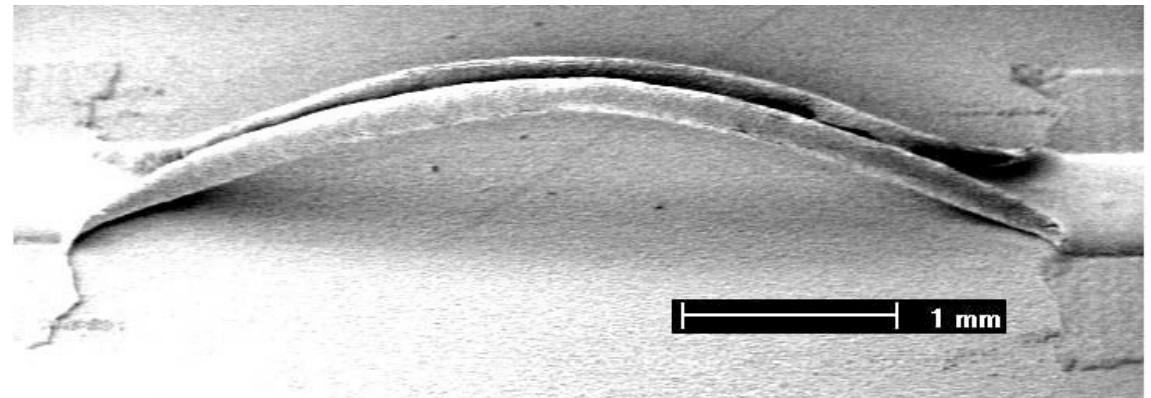
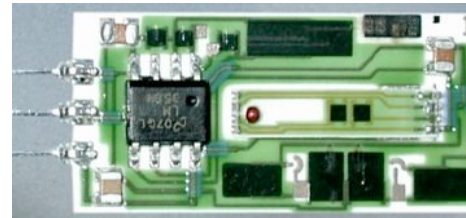
Outline

1. Introduction - **3D structuration & techniques**
2. Glass sealing - **thick-film microfluidics**
3. Directly cutting LTCC - **“large-channel” microfluidics**
4. Carbon-based sacrificial layers - **processing & features**
5. Mineral sacrificial layers - **first experiments**
6. Conclusions & outlook

1. Applications

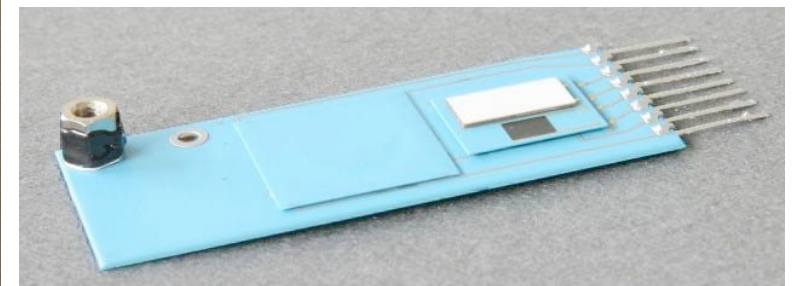
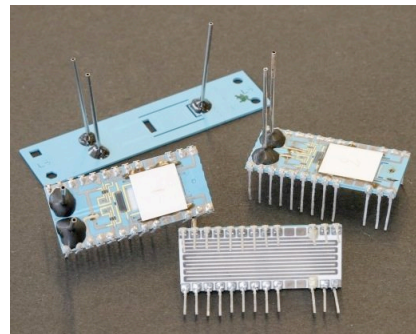
■ Sensors

- Micro-force sensor
- Suspended thermistor



■ Fluidics

- Chemical reactor
- Gas viscosity sensor



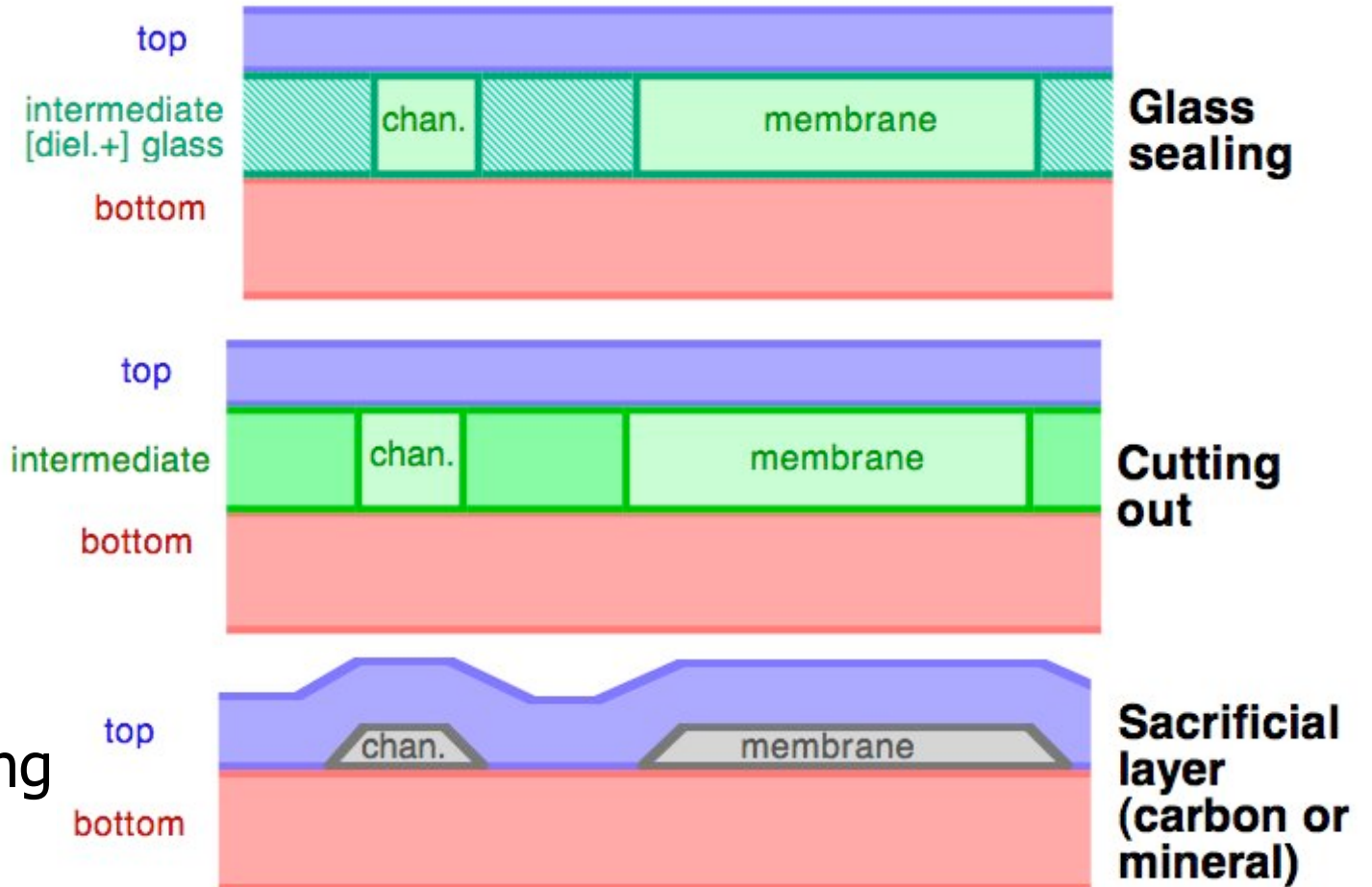
1. Structuration methods

Features

- Vias
- Channels
- Membranes
- Beams

Three types

- 1) Glass sealing
- 2) Cutting & stacking
- 3) Sacrificial layer

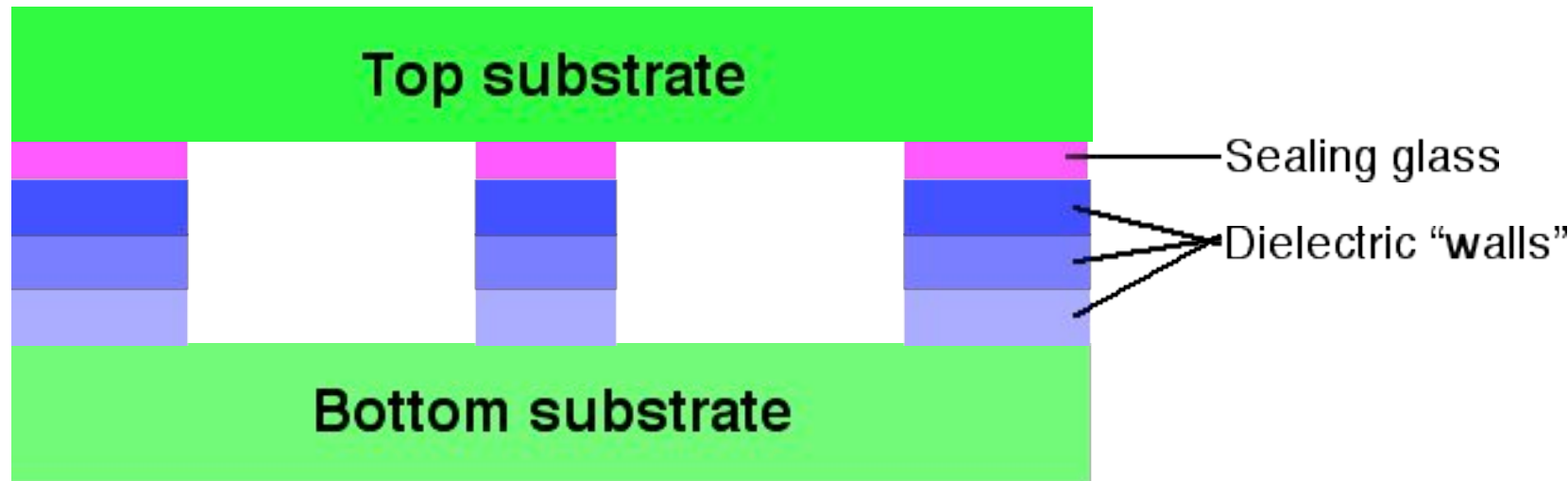


1. LTCC vs. alumina for sensors

Material	LTCC (DP 951)	Al ₂ O ₃ (96%)	Ratio
Minimal thickness [mm]	0.04	0.17	0.24
Short-term strength [MPa]	320	600	0.53
10 year strength [MPa]	110	270	0.41
Young's modulus [GPa]	110	320	0.34
Thermal conductivity [W/m]	3	25	0.12
Design strain [ppm]	1'000	800	1.25
Flexural sensitivity [kN ⁻¹]	5.68	0.11	53
Thermal resistance [K/W]	8'333	235	35

> LTCC for Thermal, low-range mechanical sensors

2. Thick-film fluidics: glass sealing



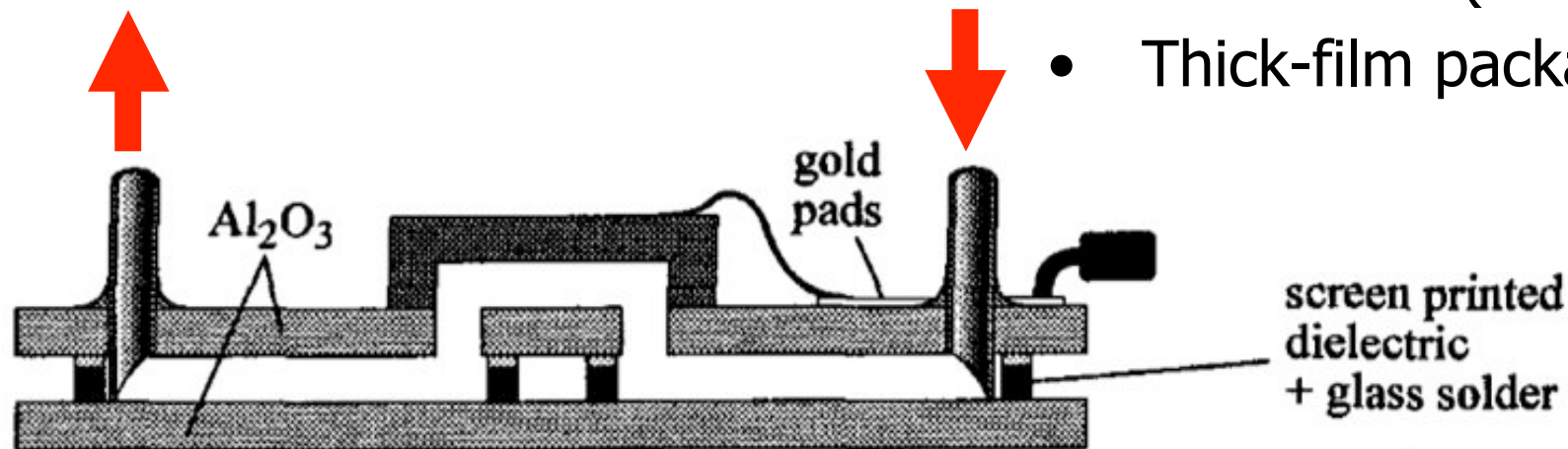
- Alumina bottom substrate
- Walls built-up by thick-film dielectric
- Final layer = sealing glass
- Glass sealing of top substrate
- Max practical height: ca. 100 μm
- Simple circuits (1 layer)

2. MEMS microreactor

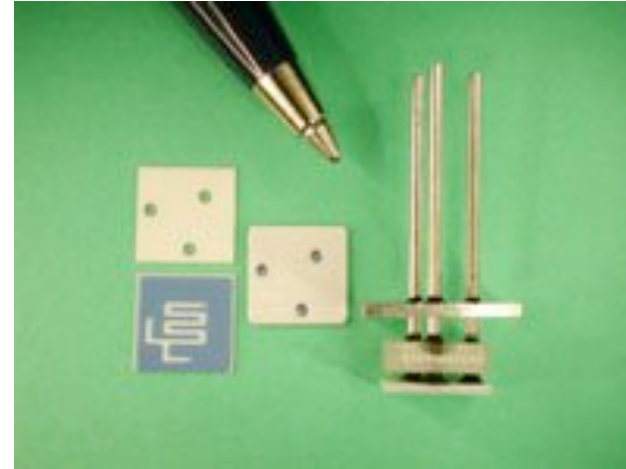
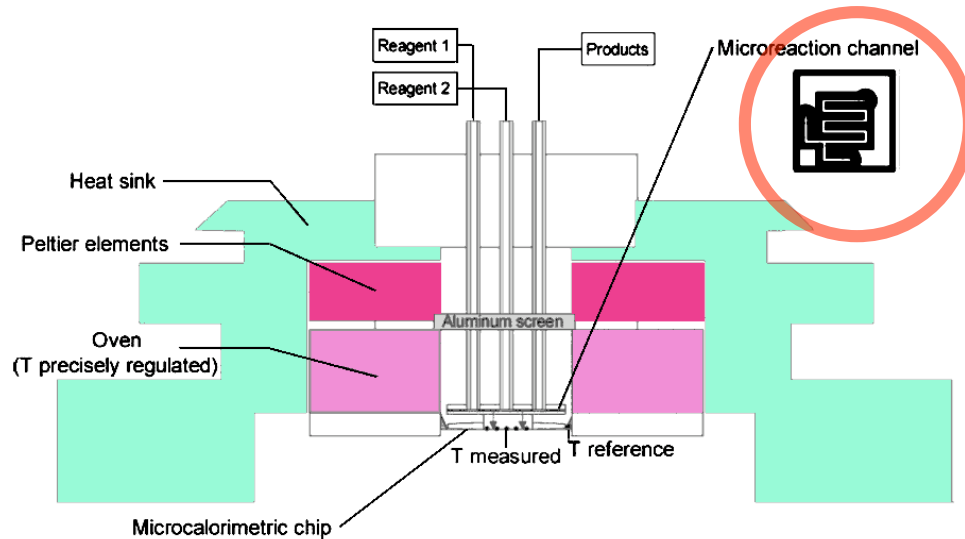
(Ch. Alépée - LMIS, 2000)



- MEMS microreactor for methanol dehydrogenation into formaldehyde
- Reaction catalysed by Na around **800°C**!
- Inlets / outlets must be at ca. **300°C** (Na vapour)!
- Thick-film packaging



2. Microreactor-calorimeter

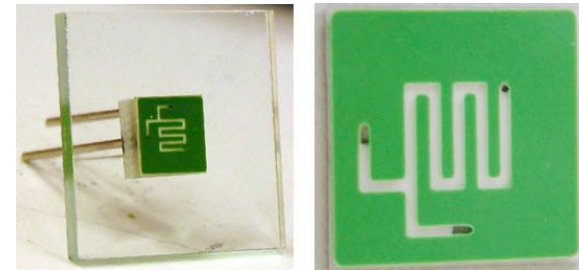


- MEMS microcalorimeter
- Thick-film glass-sealed microreactor
- Alumina...
- ...or glass

(M.-A. Schneider - 2004)

2. Glass sealing - conclusions

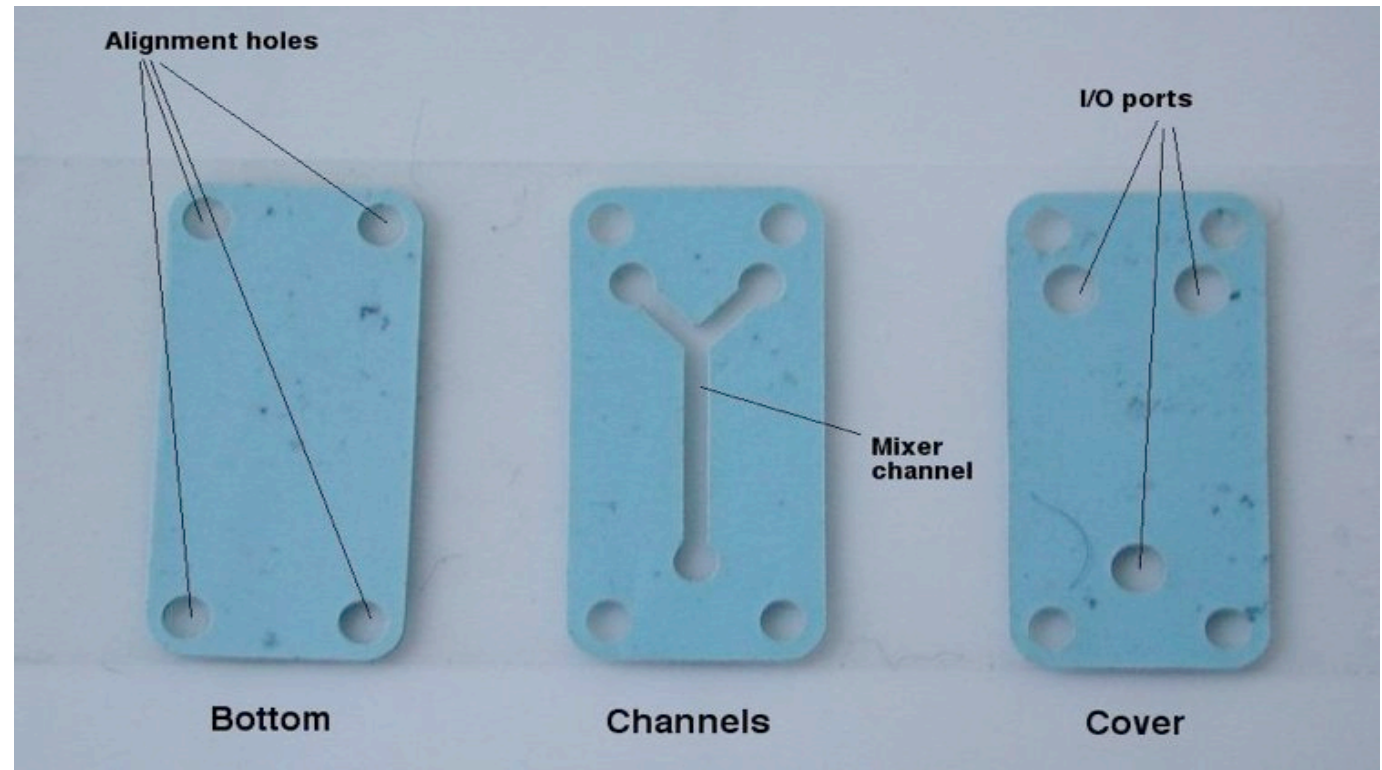
- + Proven technique
 - + Straightforward processing
 - + Very flexible: ceramic, Si, glass, ...
 - Tedious if high channels needed
 - Practically limited to 1 fluidic layer
 - Lower chemical & thermal stability
 - Often lead-bearing glasses for low processing temperatures
-
- Assembly & sealing of MEMS
 - Transparent modules - glass



3. Cutting & stacking LTCC

Process

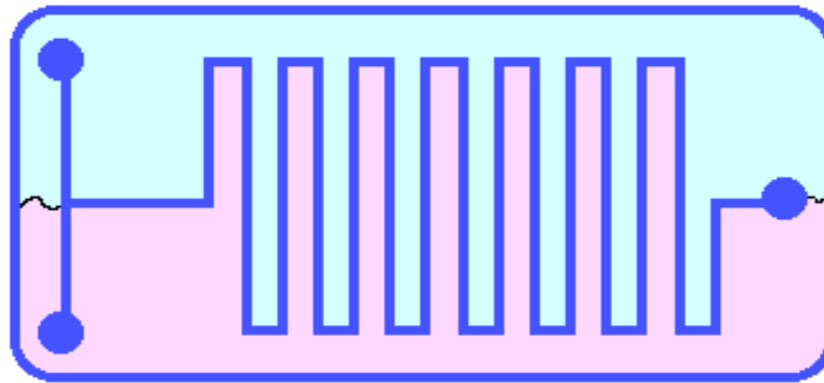
1. Cutting
2. Stacking & laminating
3. Firing



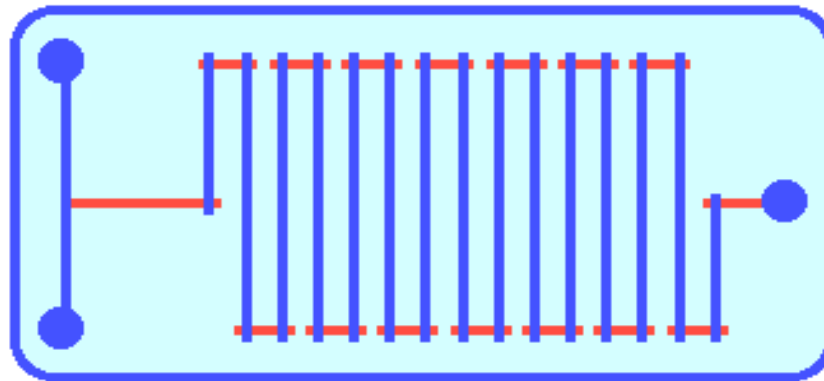
A simple LTCC micromixer

3. Meanders & complex circuits

Fabrication of complex LTCC fluidics



- LTCC sheet weak
- Strong risk of clogging



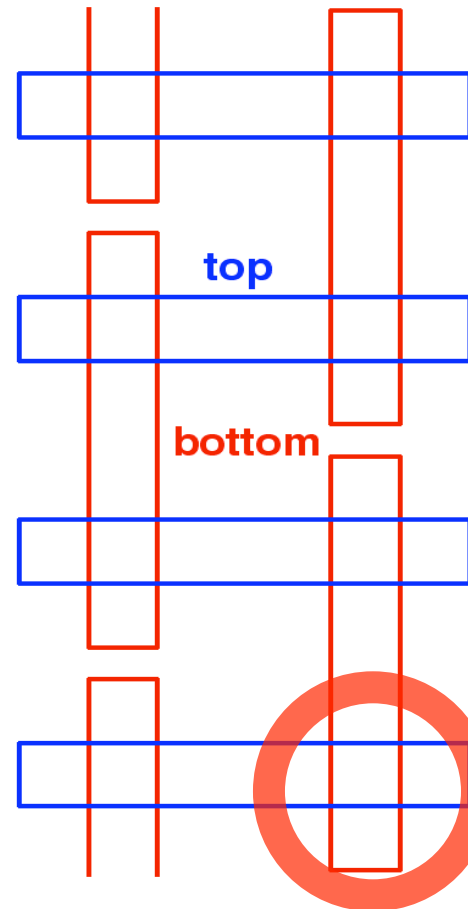
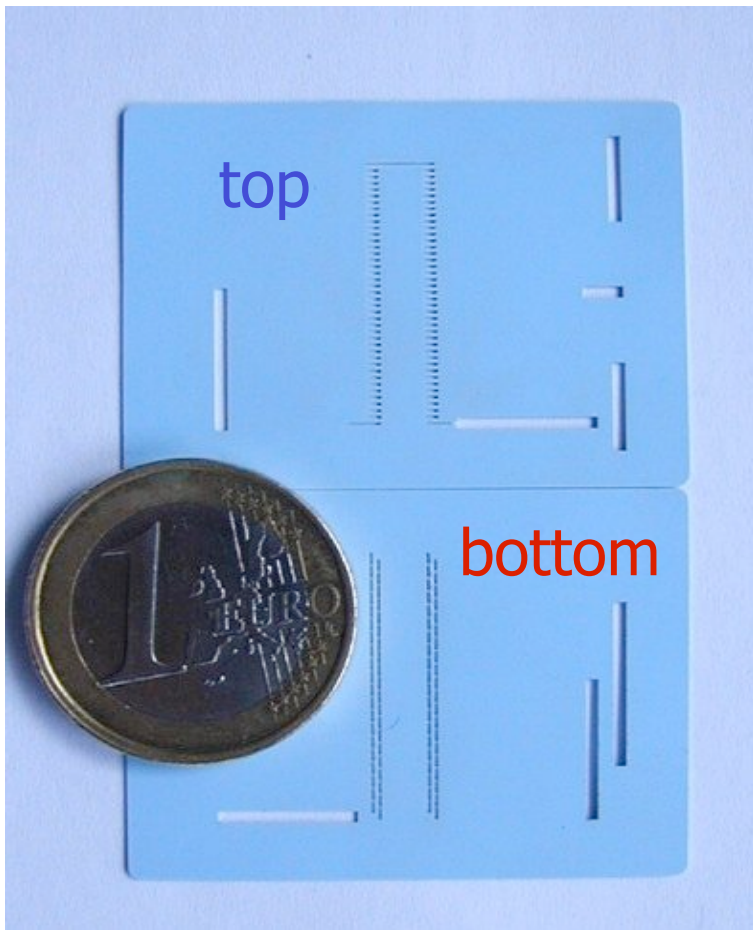
- LTCC sheet stronger
- Less risk of clogging

■ Sheet 1 (top)
■ Sheet 2 (bottom)

⇒ Avoid long, narrow & windy cuts!

3. Meanders: zig-zag micromixer

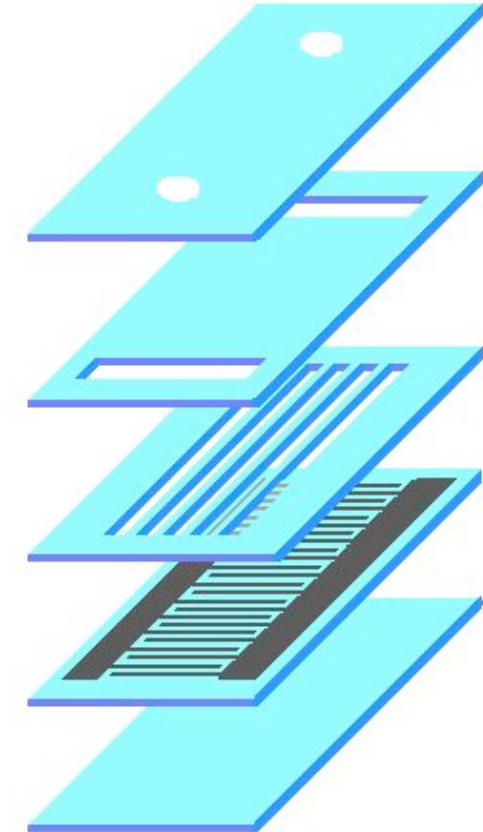
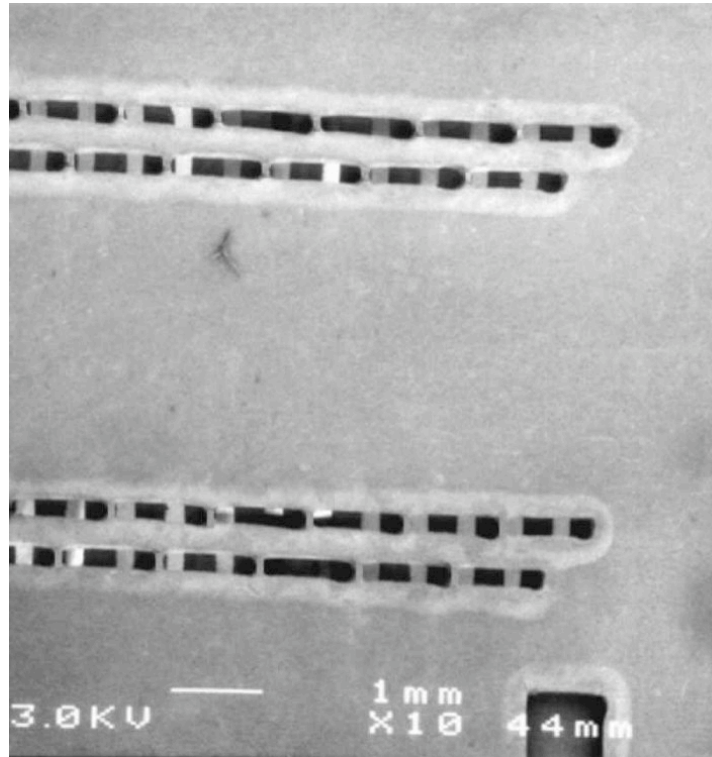
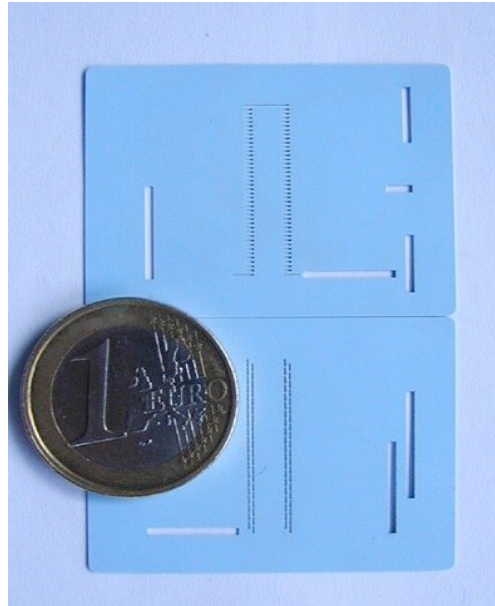
V. Mengeaud, EPFL 2002



- Two-layer “zig-zag” mixer
- Preserves integrity of LTCC layers
- Extra length: alignment tolerances

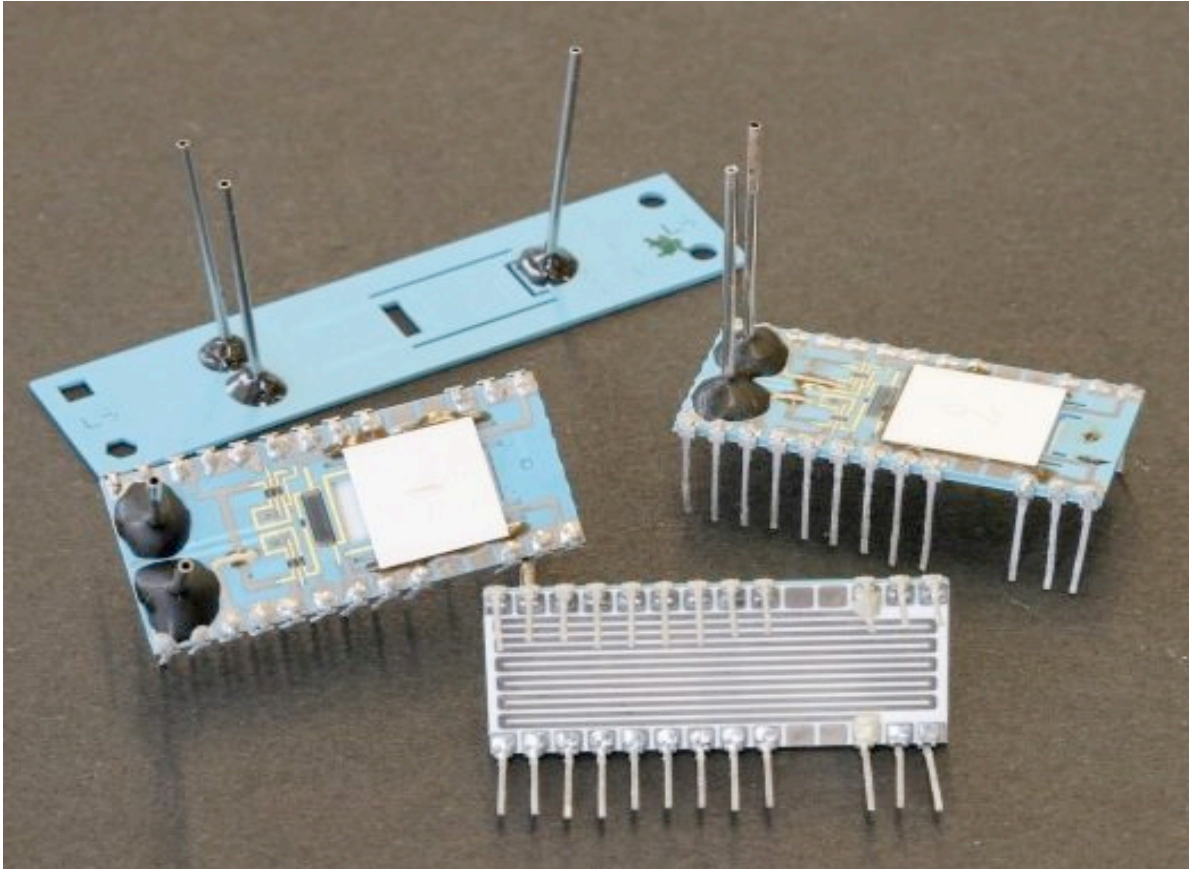
3. Meanders: zig-zag micromixer 2

V. Mengeaud, EPFL 2002



- Reliable structure, no clogging
- + electrodes: electrochemical microreactor

3. Meanders: microcalorimeter

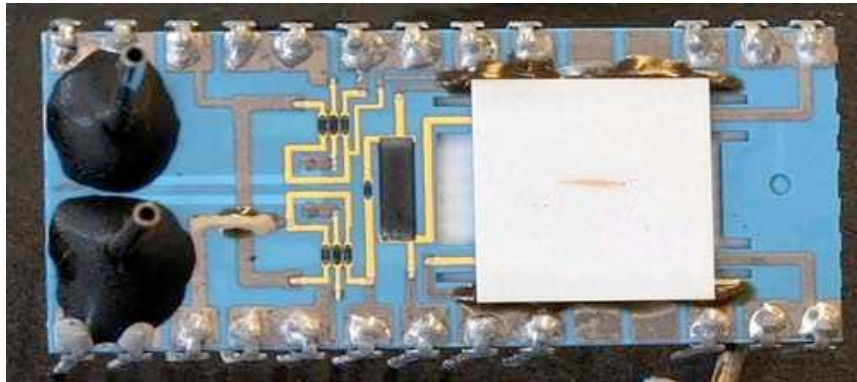


Features:

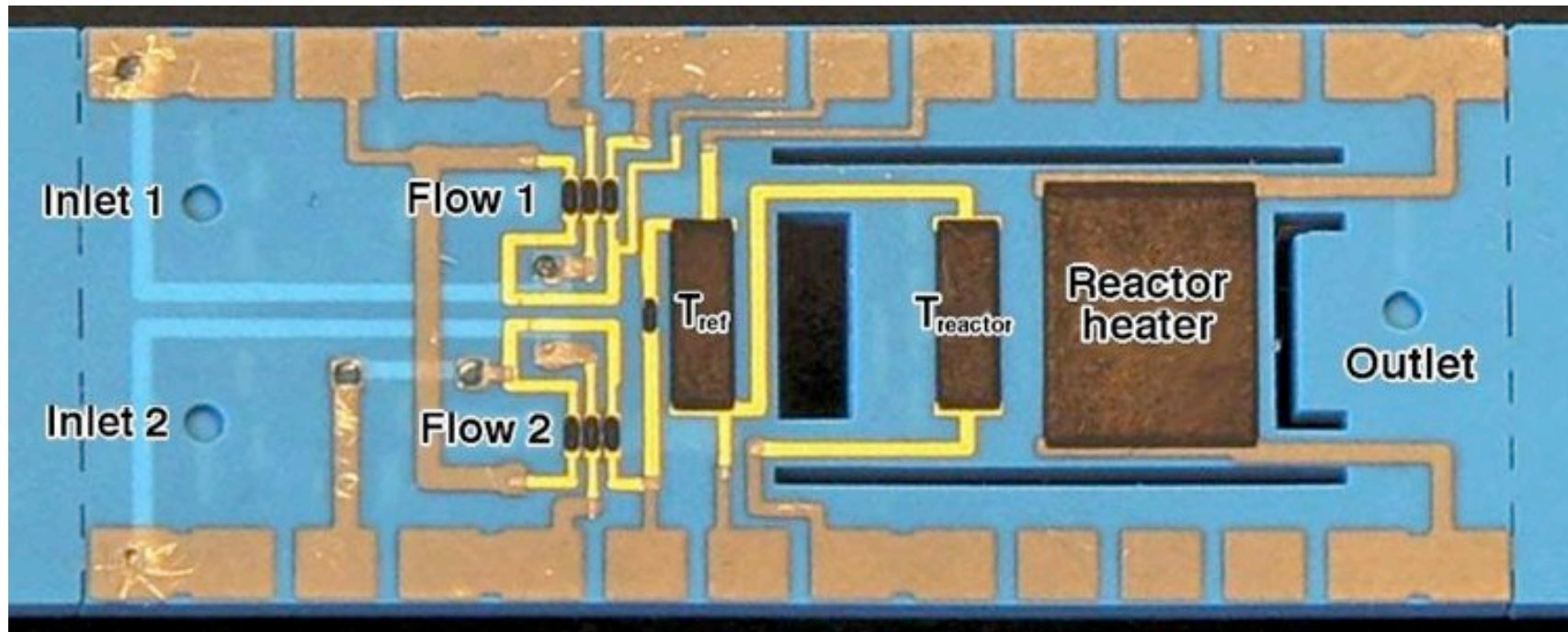
- DIL-24 package
- Global heating track
- Inlet pre-heating zones (meanders)
- Thermally insulated reaction zone
- Microcalorimeter with calibration heater
- Separate flow sensor for each inlet

Willigens, 2005

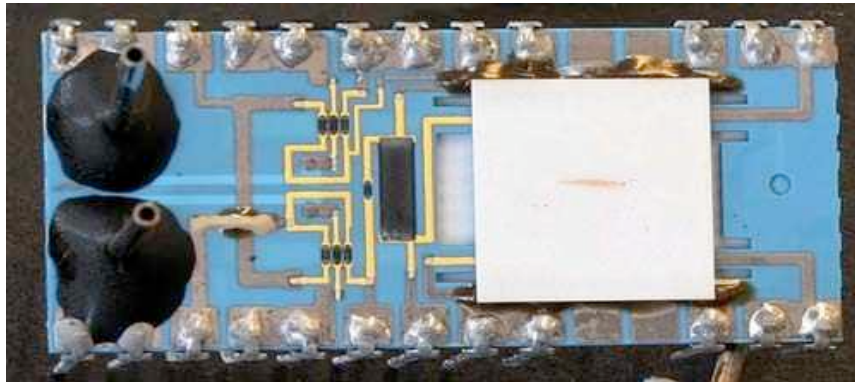
3. Meanders: microcalorimeter 2



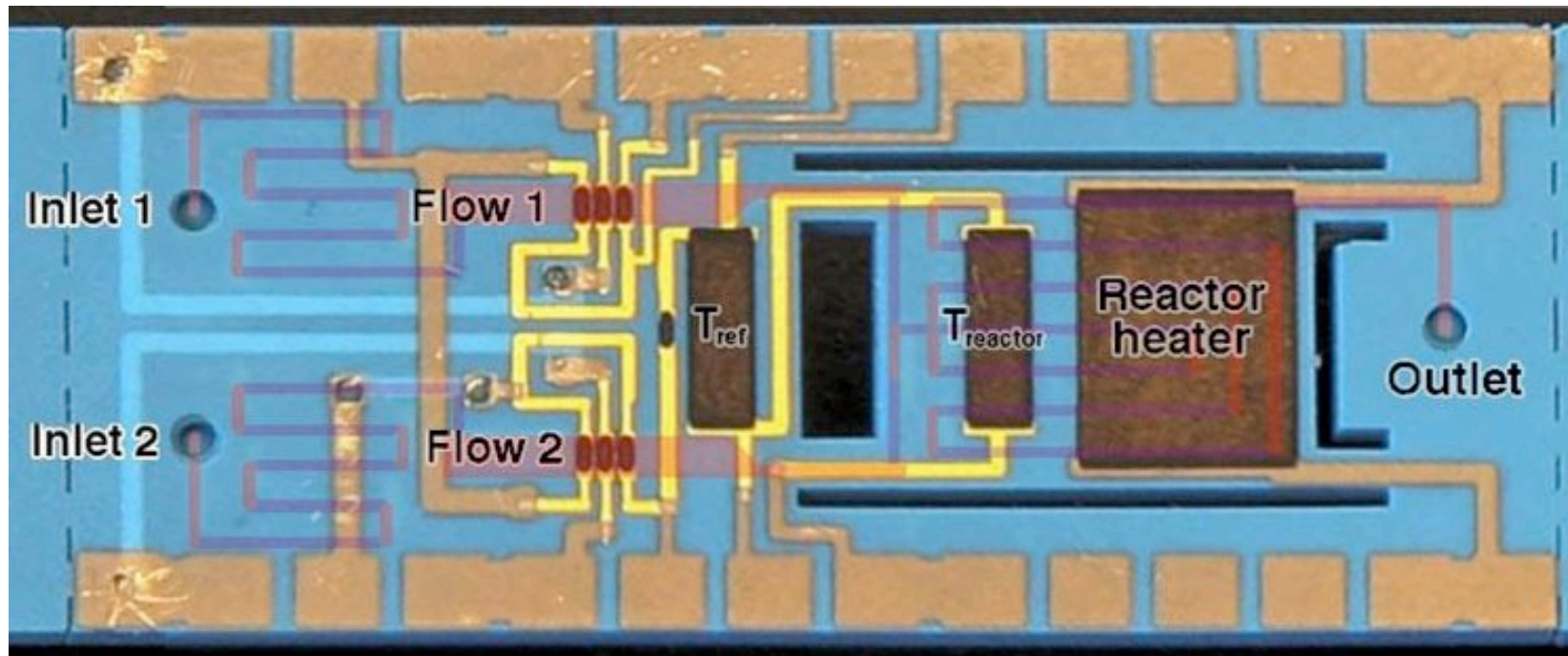
- Complete reactor
- LTCC: elements



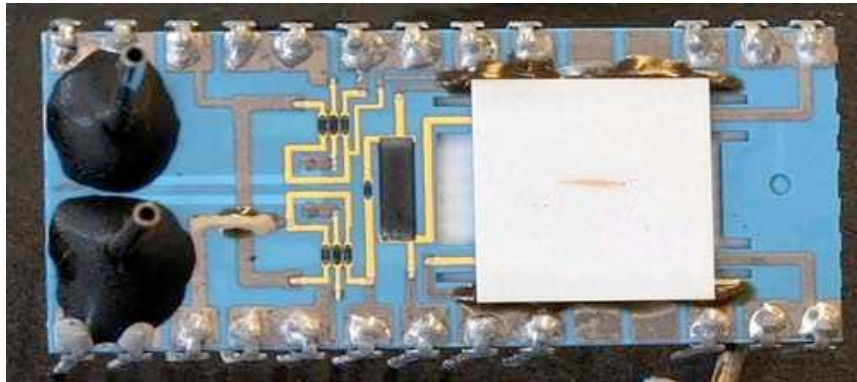
3. Meanders: microcalorimeter 3



- Complete reactor
- LTCC: elements
- **LTCC: fluidic layout**

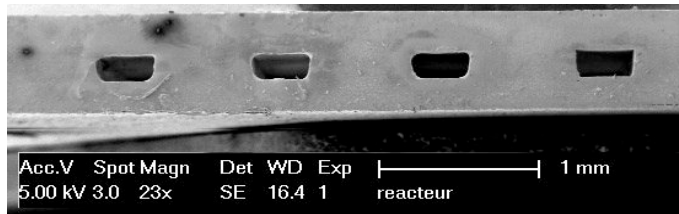


3. Meanders: microcalorimeter 4

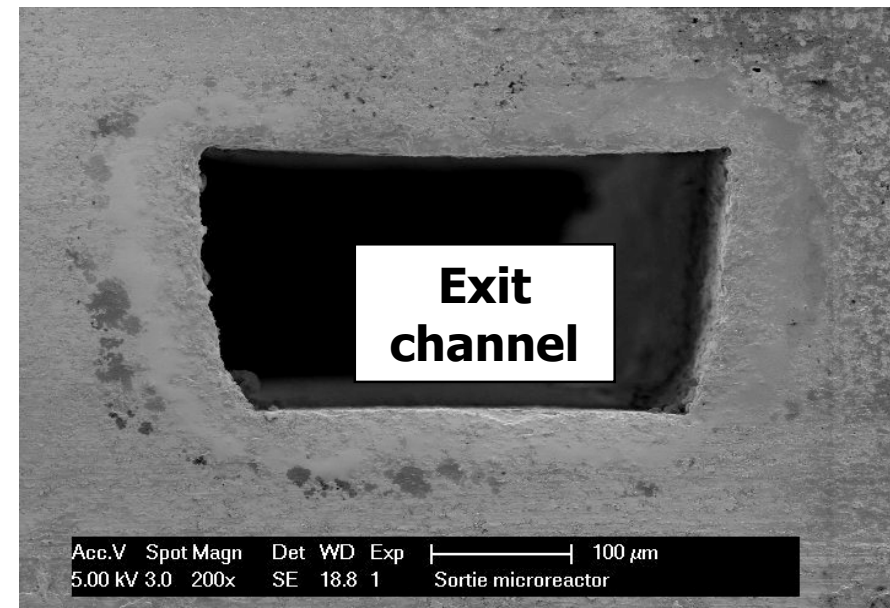
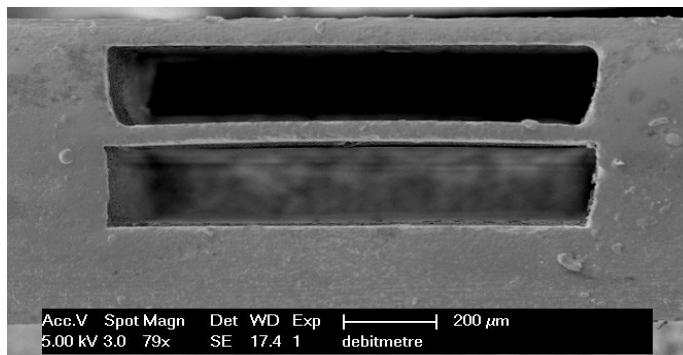


- Complete reactor
- LTCC: elements
- LTCC: fluidic layout
- LTCC: layers & lamination

**Reaction
zone**



**Flow
meter**

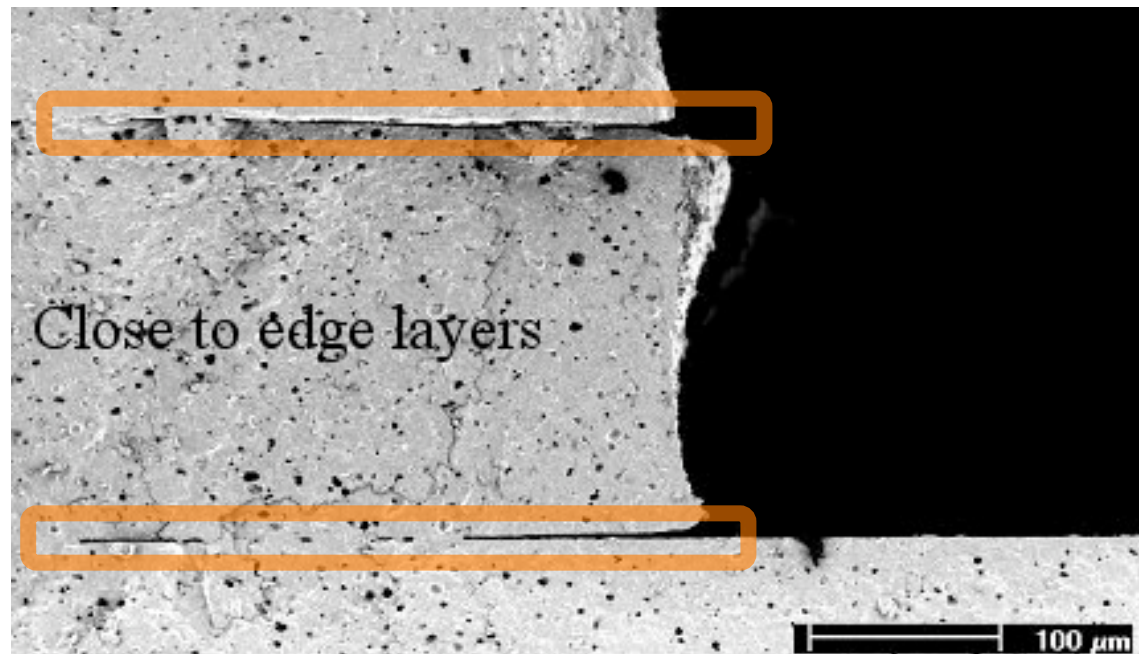
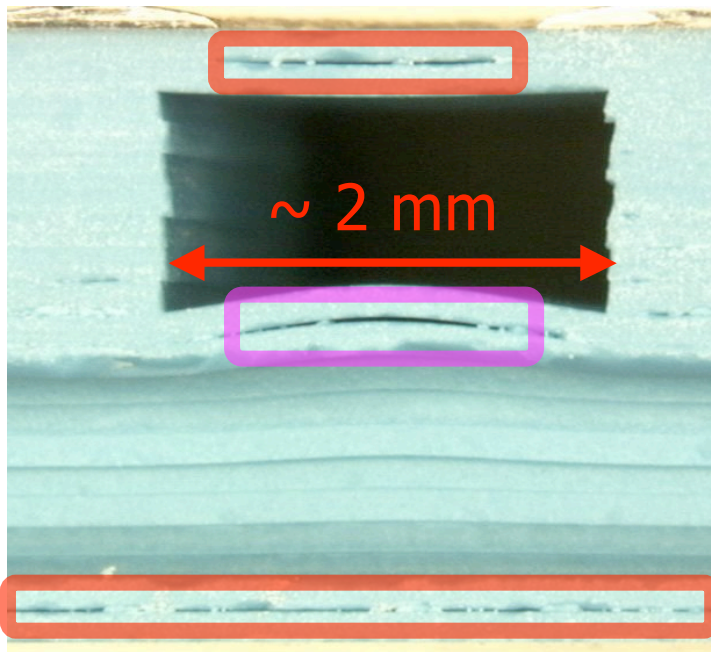


3. Fluidics: lamination quality

Zones with reduced lamination pressure:

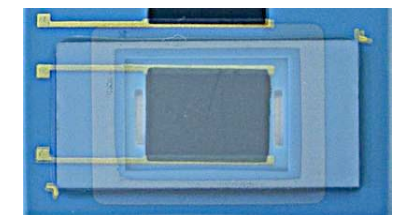
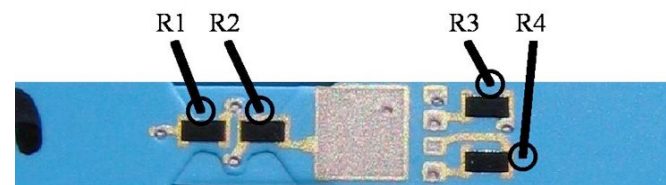
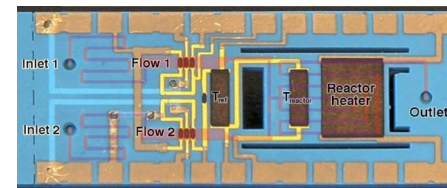
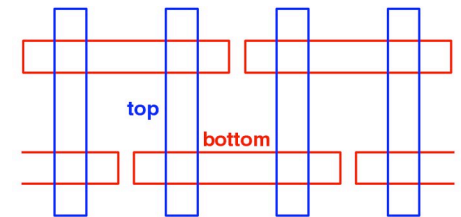
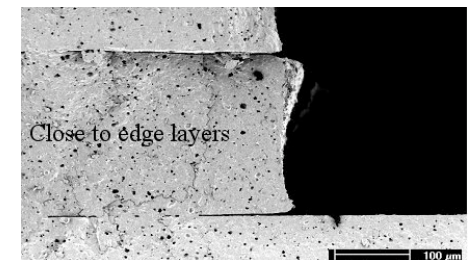
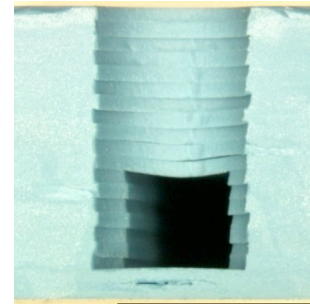
→ **low-pressure lamination!**

- Above & below channels
- Crossings
- Edges



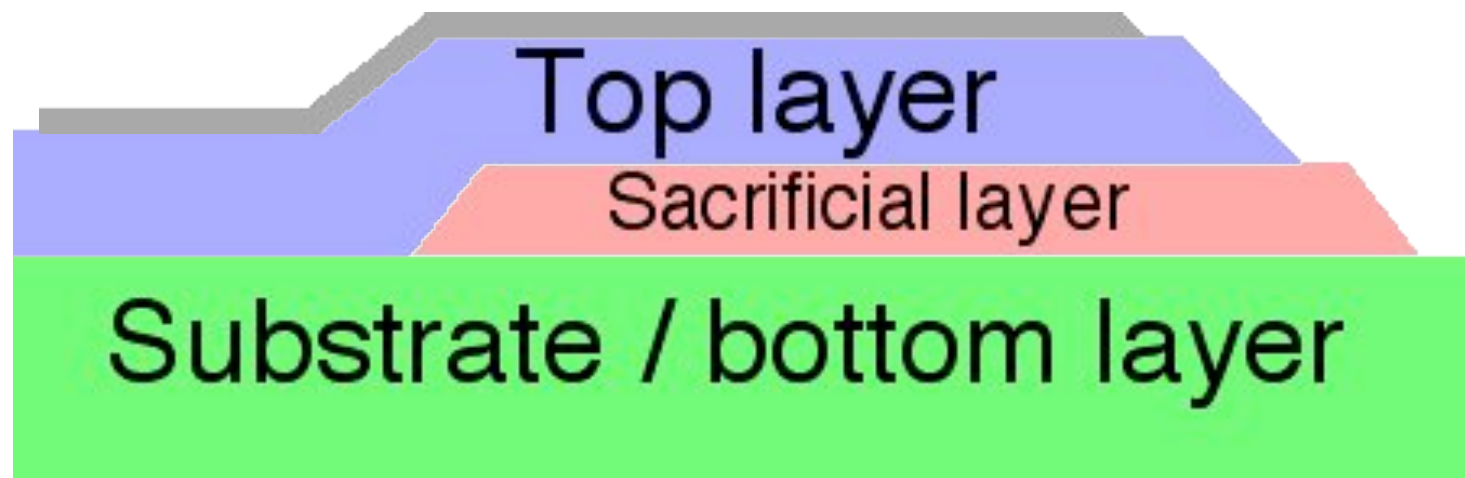
3. Cutting & stacking - conclusions

- + Very simple technique
- + Straightforward processing
- + Can achieve large channels
- Quality problems with large channels w/o inserts
- Alignment tolerances → small dead zones
- Microreactors
- Suspended heaters (gas sensors)
- Structured cantilevers



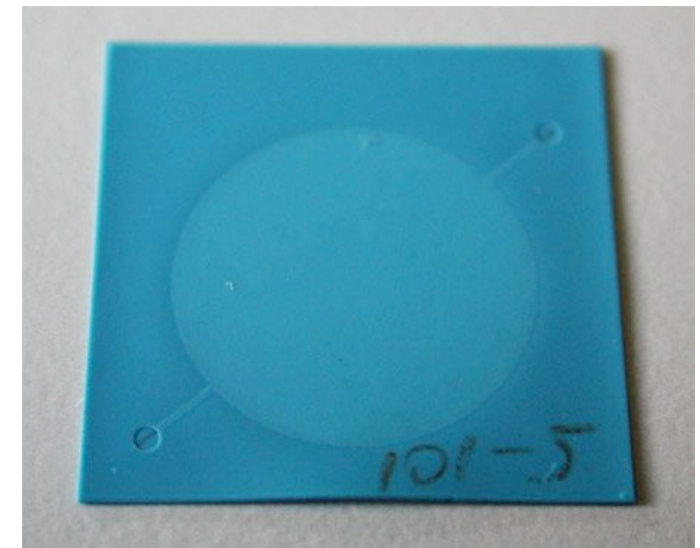
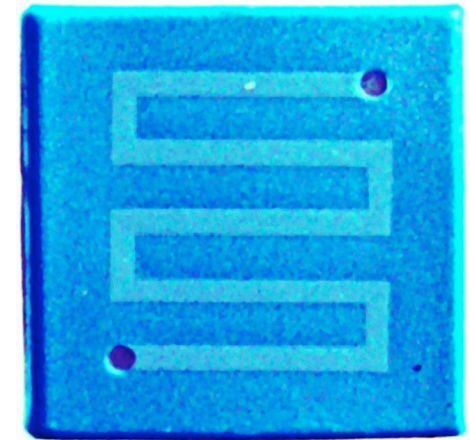
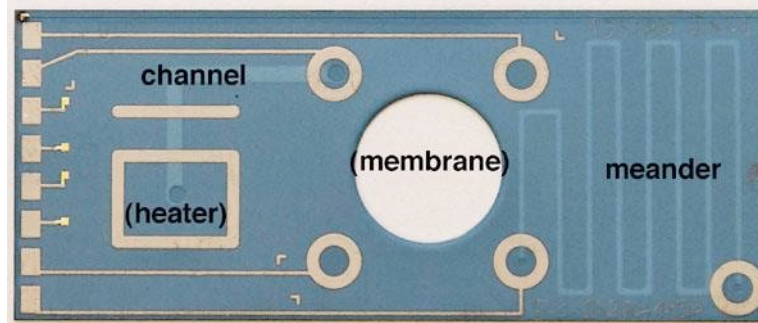
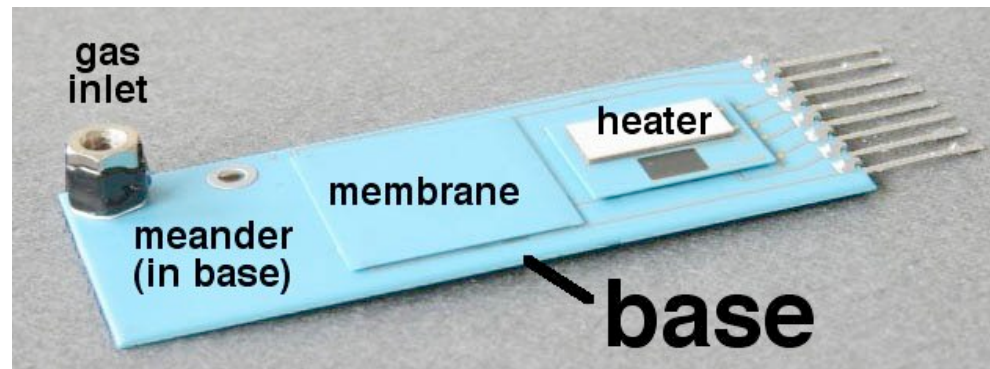
4. Carbon sacrificial layers - process

- Print [fire] sacrificial paste onto LTCC / ceramic substrate
- Laminate (LTCC) / print (ceramic) top layer
- Fire structure in air / O₂, OR:
- Fire structure in neutral gas & oxidise later
- Post-processing



4. Carbon layers - applications

- Fluidic resistors
- Membranes
- Gas viscosity sensor
- Carbon: membrane & meander

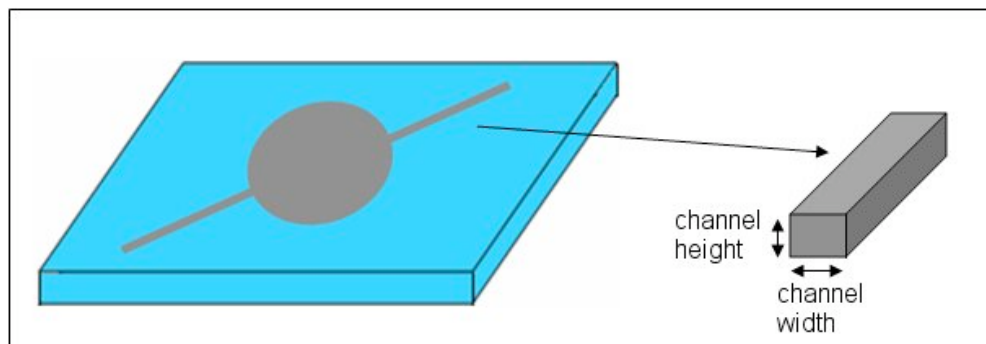


4. Carbon layers - membrane issues

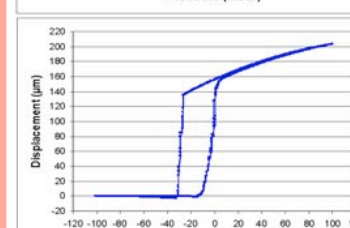
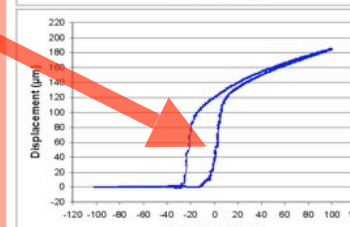
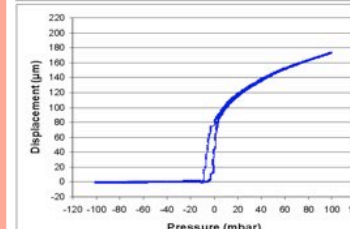
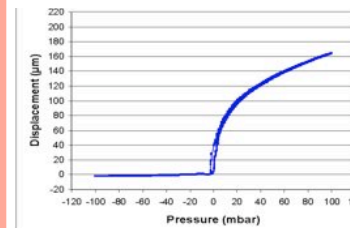
- LTCC membrane: 3x support + 1 thin (50 μm) DP 951 tapes
- Channel width (2:1) & height (2:1)
→ **Strong change of properties**



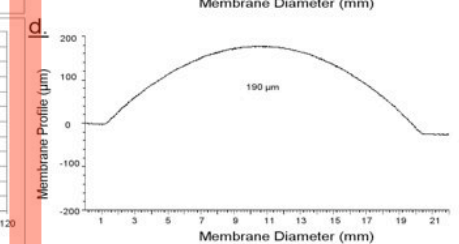
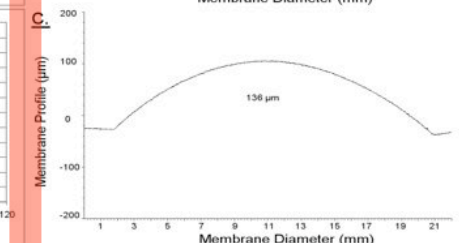
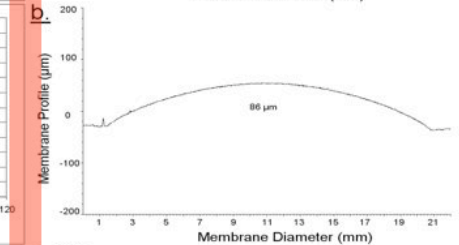
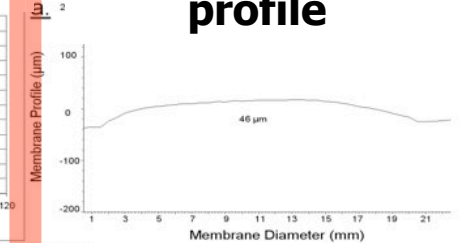
Hysteresis



Pressure-displacement

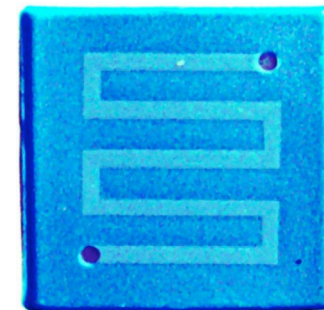
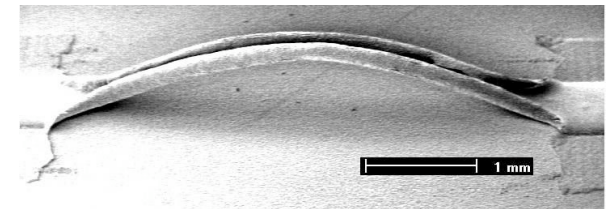
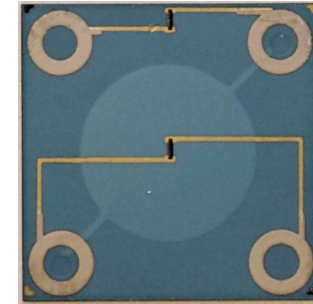


Membrane profile



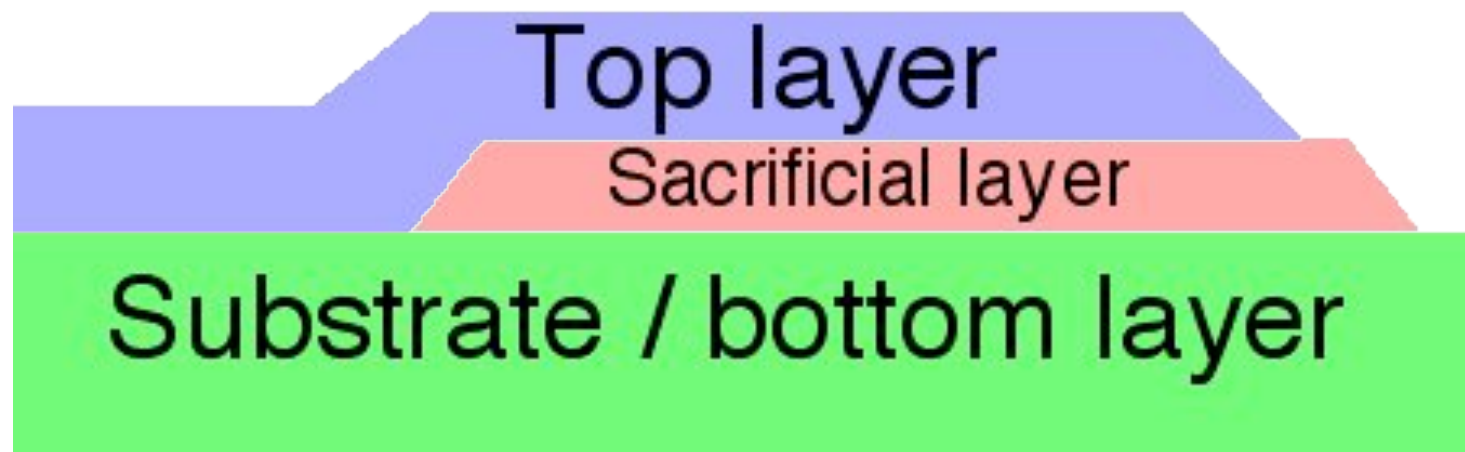
4. Sacrificial carbon - conclusions

- + Simple processing
 - + No lamination problems
 - + Thin & large membranes achieved
 - Very process sensitive for membranes
 - LTCC: swelling, sagging
 - Thick film: sagging, lateral shrinkage, curling
 - Limited thickness compared to cutting
-
- Microfluidics, fluidic “resistors”
 - Membranes



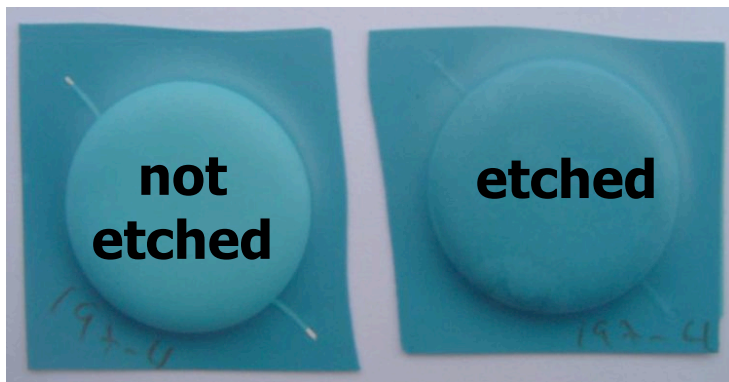
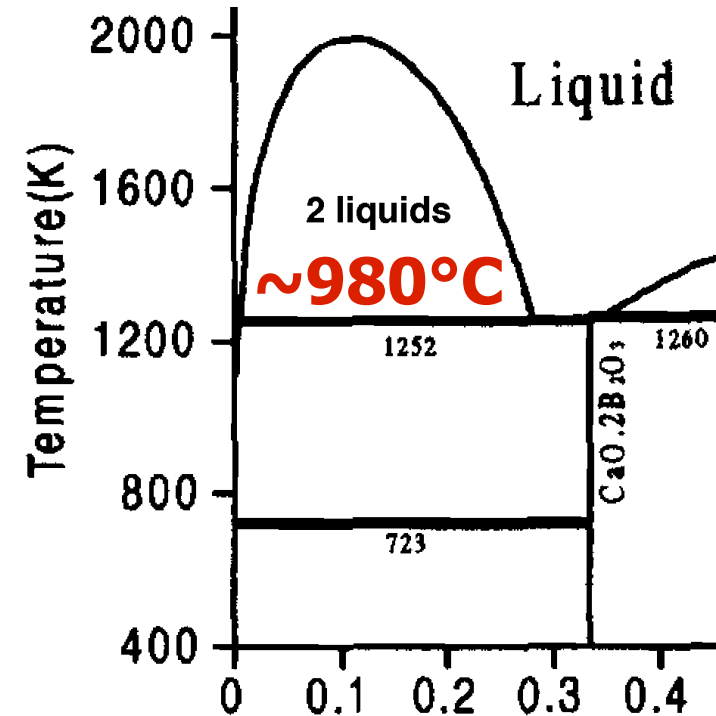
5. Mineral sacrificial layers - process

- Print [fire] sacrificial paste onto LTCC / ceramic substrate
 - Laminate (LTCC) / print (ceramic) top layer
 - Fire structure
 - Chemically etch sacrificial layer
- Requires relatively “open” structure

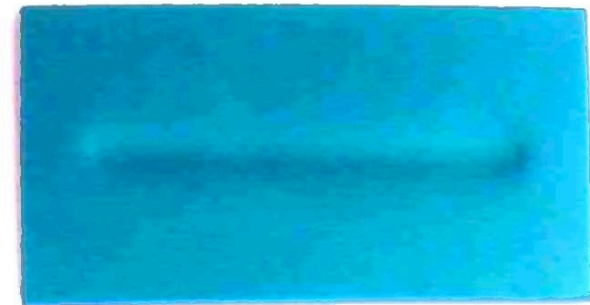


5. Mineral layers - $\text{CaO} + \text{B}_2\text{O}_3$

- For dissolution in acids: basic system
- Filler: CaO or CaCO_3
- Glass: B_2O_3 or borax ($\text{Na}_2\text{B}_4\text{O}_7$)
- **$\text{CaO} - \text{B}_2\text{O}_3$** : low shrinkage (ca. 8%)
- Sintering hindered by $\text{CaO}-\text{B}_2\text{O}_3$ reaction?
- Deformed LTCC
- Very good dissolution in acids



Sintered LTCC +
paste



5. Mineral layers - CaO + borax

- B_2O_3 replaced by borax ($Na_2B_4O_7$)
 - Reduced B_2O_3 volatility
 - Melting at $\sim 740^\circ C$
 - Dense & good cohesion with enough borax
- **Capacitive force sensor** (thick-film dielectric + conductor)

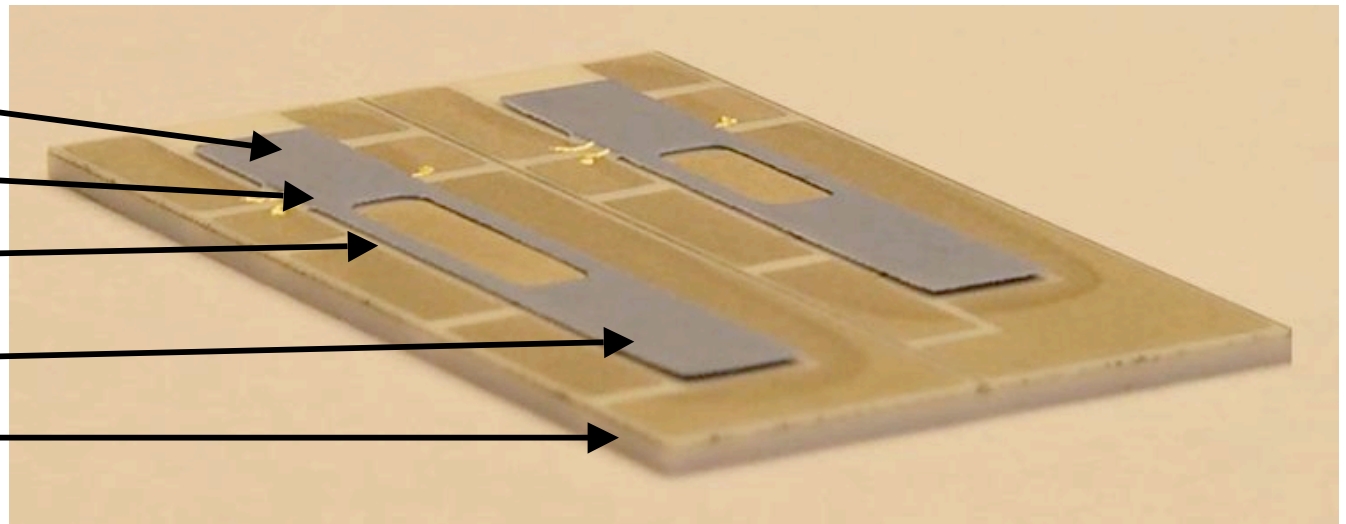
Reference

Attachment

Hinges

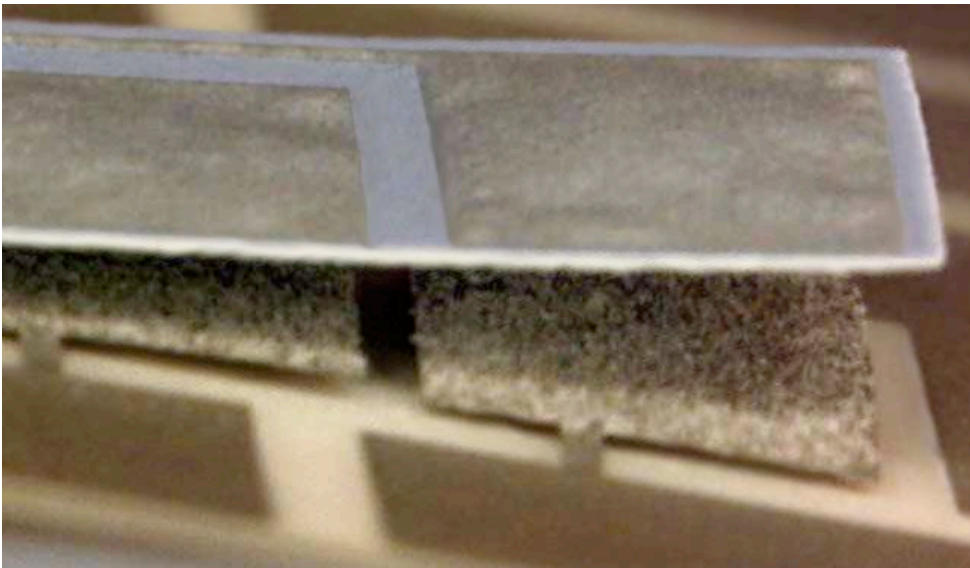
Plate (+ conductor)

Alumina base



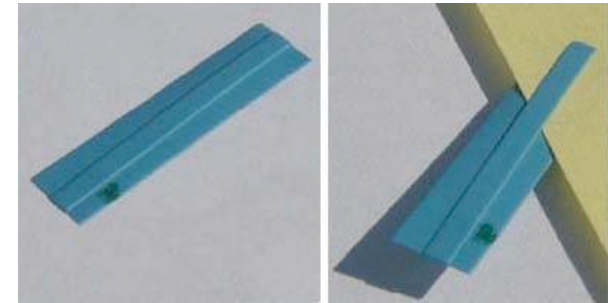
5. Mineral layers - issues

- Strong reaction with LTCC & thick films (Na)
 - Difficult to remove by etching
 - Peeling of conductor under sacrificial paste upon etching (Na)
- **Only small amounts of alkali oxides allowable**



5. Mineral layers - conclusions

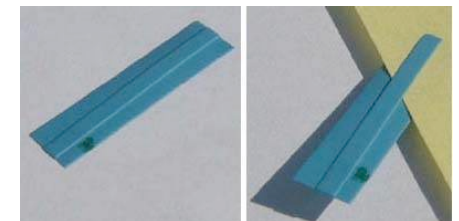
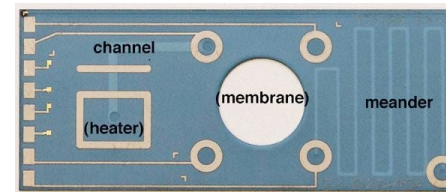
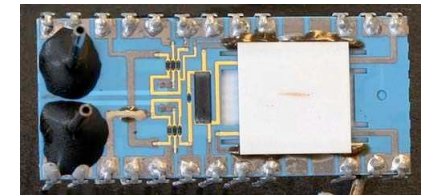
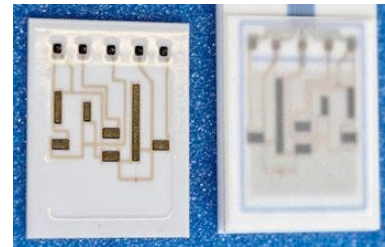
- + Universal: LTCC, thick-film, glass, ...
 - + Straightforward processing
 - + No lamination problems
 - + No sagging / swelling during firing
-
- Need etching + cleaning steps
 - Reactions with other layers
 - Shrinkage matching needed on LTCC
-
- Open structures: cantilevers, bridges,...
 - **Work in progress !**



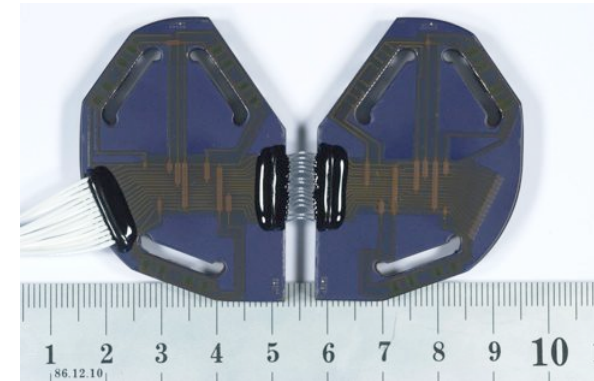
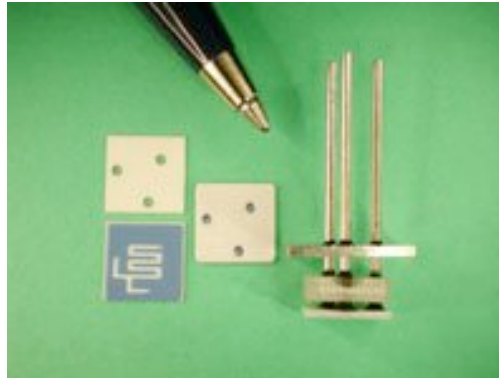
6. Conclusions

Wide range of methods available:

- **Glass sealing (+ dielectric)**
 - Hermetic sealing
 - Simple fluidics (1 layer)
- **Cutting & stacking**
 - Fluidics (large); reactors
 - Structured mechanical sensors
- **Carbon- & mineral-based sacrificial layers**
 - Complex fluidics
 - Micromechanical structures



Merci



Thank you !

